

FPGA Cyclone® Family 20060 Cells 275.03MHz 130nm Technology 1.5V 400-Pin FBGA

Manufacturers	Altera Corporation (Intel)
Package/Case	FBGA-400
Product Type	Programmable Logic ICs
RoHS	Rohs
Lifecycle	



Images are for reference only

Please submit RFQ for EP1C20F400C8N or [Email to us: sales@ovaga.com](mailto:sales@ovaga.com) We will contact you in 12 hours.

[RFQ](#)

General Description

EP1C20F400C8N appears to be a part number for an FPGA (Field-Programmable Gate Array) manufactured by Intel (formerly Altera). Here's some information about it:

Features

- FPGA (Field-Programmable Gate Array) with 1,920 logic elements (LEs)
- 400 MHz maximum operating frequency
- 8 input/output (I/O) banks with support for various I/O standards such as LVDS, LVTTTL, and SSTL
- 3.3V or 2.5V I/O voltage options
- Embedded memory blocks, including M9K memory blocks for storing data
- On-chip PLL (Phase-Locked Loop) for clock management
- Support for configuration through various methods such as JTAG, serial, and parallel configuration
- Built-in digital signal processing (DSP) blocks for high-performance signal processing
- Support for various design entry methods including schematic capture and hardware description languages (HDL) such as Verilog and VHDL

Application

- Embedded systems
- Digital signal processing (DSP)
- Communications systems
- Industrial automation
- Video and image processing
- Aerospace and defense applications
- Networking and telecommunications



CAUTION

This bag contains
MOISTURE - SENSITIVE DEVICES

LEVEL
3

1. Shelf life in sealed bag : 18 months minimum at < 40°C and < 90% relative humidity (RH)
2. After bag is opened, devices that will be subjected to vapor - phase reflow, or equivalent processing (peak package body temperature of 260°C) must be :
a) Mounted within : 168 hours at factory conditions of ≤ 30°C / 60% RH, or b) Stored at ≤ 10% RH
3. Devices require baking before mounting if:
a) Humidity indicator card show humidity > 10% when measured at 23 ± 5°C, or b) Condition 2a or 2b is not mwmt.
4. If baking is required, devices may be baked for :
a) 12 hours at 125°C +/- 5°C for high temp. device containers.
b) Baking at 40°C +5°C/- 0°C and < 5% RH for low temperature device containers is **NOT RECOMMENDED**

Bag Seal Date (MM-DD-YY) : 09-26-2011
Note: LEVEL defined by IPC/JEDEC J-STD-020

2nd Level Interconnect

1. RoHS Compliant - Category: e3
 2. Maximum safe rework temperature: 260 °C
- For Rework: mount within 8 hours at factory conditions of ≤ 30°C / 60%RH

ALTERA

ORIGIN : KOREA

PART # : EP1C20F400C8N

LOT # : VCH9S42723

FAC # : AT13238A

D/C : L CCH9S1137A

TRACE
CODE: 3R1LA1Q0L

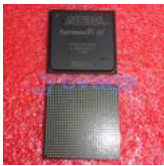
QTY: 200 240

PK : P3

092611 13:14



Related Products



[EP4CE55F29C8N](#)

Altera Corporation (Intel)

FBGA-780



[EPM1270T144A5N](#)

Altera Corporation (Intel)

TQFP-144



[EP2C35F672C8N](#)

Altera Corporation (Intel)

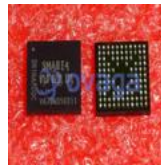
FBGA-672



[EP2C35F484C7N](#)

Altera Corporation (Intel)

FBGA-484



[EPM240M100C5N](#)

Altera Corporation (Intel)

BGA-100



[EPM570F256C5N](#)

Altera Corporation (Intel)

FBGA-256



[EPM7128AETC100-10](#)

Altera Corporation (Intel)

TQFP-100



[EP2C35F484I8N](#)

Altera Corporation (Intel)

FBGA-484